

	Hit s	Search Text	DBs
35	749	((substrate or wafer) same (ITO or (transparent near4 conductive near6 layer) or (indium near4 tin near4 oxide)) same (resist or photoresist) same (lithography or expos\$4 or irradiat\$4 or illuminat\$4)) and develop\$4 and (etch\$4 near28 (dry or RIE or plasma))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
36	79	S33 and S35	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
37	45	S36 NOT S34	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
38	76	((substrate or wafer) same (resist or photoresist) same (methacrylate or acrylate or polycarbonate or polyimide) same (lithography or expos\$4 or irradiat\$4 or illuminat\$4)) and (develop\$4 same (pattern or mask) same (plat\$4 or metalliz\$5)) and ((plat\$4 or metallization) same strip\$4 same (base or basic or developer))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB